

SOT1036-1

plastic thermal enhanced ultra thin quad flat package; no leads; 76 terminals; UTLP based; body 6 x 6 x 0.55 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HUQFN76U
Package type industry code	HUQFN76U
Package style descriptive code	HUQFN (thermal enhanced ultra thin quad flatpack; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	1-12-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.9	-	6	6.1	mm
E	package width		5.9	-	6	6.1	mm
A	seated height		[tbd]	-	0.55	0.6	mm
A ₂	package height		[tbd]	-	0.55	[tbd]	mm
n ₂	actual quantity of termination		-	-	76	-	



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2. Package outline

HUQFN76U: plastic thermal enhanced ultra thin quad flat package; no leads; 76 terminals; UTLT based; body 6 x 6 x 0.55 mm

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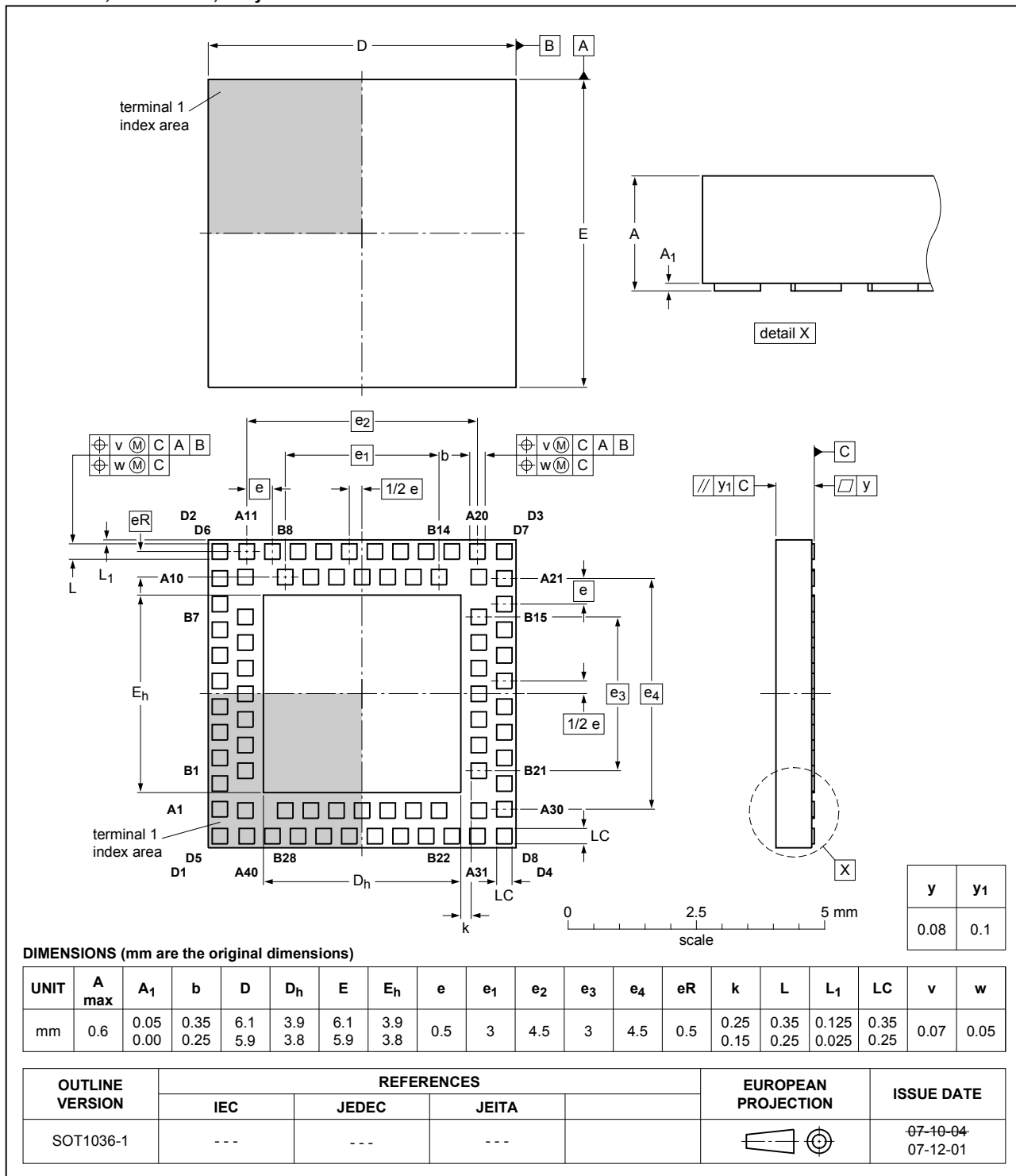


Fig. 1. Package outline HUQFN76U (SOT1036-1)

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3. Legal information

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